



IEEE

Online & Onsite : Avanti Kyoto Hall, Kyoto, 16th~17th Nov., 2023

IMFEDK 2023

The 2023 International Meeting for Future of Electron Devices, Kansai

Paper submission deadline

Extended: Sept. 16th 2023



[Presentation]

[Oral]

- Invited - Onsite or Online
- Contributed - Onsite

[Poster]

- Contributed - Onsite

[Attendance]

[Oral]

- Onsite or Online

[Poster]

- Onsite

[Registration fee]

[Presenters (excluding Invited)]

¥5,000

[Others]

Free !!

Keynote speeches & Invited talks

Special Lecture

Tsunenobu Kimoto

Kyoto Univ.

Keynote

Toshiro Hiramoto

Univ. of Tokyo

Giuseppe Greco

CNR-IMM

Industry

Sadaaki Katoh

Resonac Holdings

Takuya Tsutsumi

NTT

Academia

Toshihide Ide

AIST

Shigeto Sato

Tohoku Univ.

Takashi Matsuoka

Tohoku Univ.

Akio Yamamoto

University of Fukui

Milan Tapajna

Slovakia Academy of Science

Finalized !!

Important dates:

(1) Paper submission deadline: ~~September 2nd~~, Sept. 16th, 2023.

(2) Participation registration deadline: November 9th, 2023.

Registration information:

All attendees must send the registration sheet (downloaded at the IMFEDK site) to the conference secretary.

Travel information: Avanti Kyoto Hall is in front of the south exit of JR Kyoto station.

(1) Attendees will find many hotels around JR Kyoto stations.

(2) Foreign attendees coming from Kansai Int. Airport (KIX) are recommended to use limited express “Haruka” from KIX to JR Kyoto station due to its direct access (~90 min.).

IMFEDK Committee

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Local arrangement and management: Y. Omura (ACA)

Committee: Y. Ando (Ricoh), K. Nakahara (Rohm), K. Hayashi (Kobe Steel), S. Sato (Kansai Univ.), Y. Uraoka (NAIST), H. Nishinaka (KIT), M. Kuzuhara (Kwansei Gakuin Univ.), M. Noda (KIT), Y. Murase (Murata Manufacturing), T. Fukuda (Sekisui Chemical), A. Hiroki (KIT), S. Koba (Kobe City College Tech.), T. Maemoto (OIT), S. Soma (Kobe Univ.), M. Moniwa (TUT), N. Matsuo (Univ. Hyogo), T. Kato (Murata Manufacturing), T. Seki (Omron), H. Ishida (Panasonic), E. Kanda (Kyocera), K. Okada (Panasonic TowerJazz), S. Murakami (ORIST), Y. Murayama (Nisshinbo Micro Devices), K. Sakurano (Ricoh), M. Yoshimoto (KIT), S. Sasa (OIT), Y. Yaoi (Ishida), Y. Kamakura (OIT), A. Fukui (Sharp), T. Kimoto (Kyoto Univ.), M. Ogawa (Kobe Univ.), M. Fujii (Kindai), S. Okura (Ritsumeikan Univ.), H. Watanabe (Ricoh), M. Uenuma (NAIST)

We will take all possible precautions, but we are not responsible for the leakage of information sent to us in the unlikely event.

Paper submission information

(<http://www.ieee-jp.org/section/kansai/chapter/eds/imfedk/>)

(1) **All papers** should be submitted to the EasyChair site after the registration of the author. Please see the guidelines at the site.

(2) Keynote speeches and Invited talks

Please follow the IEEE format provided by the committee.

Paper should not exceed **4 printed pages**. The paper of 1-page is regarded as Abstract and will not be published in Xplore, whereas that of more than 2-page is regarded as Proceeding and will be published in Xplore.

(3) Oral presentation

Anyone, including students, can submit a paper as an oral presentation.

Please follow the IEEE format provided by the committee.

Paper should not exceed **2 printed pages**. The paper will be published in Xplore. All submitted papers will be reviewed by the Committee, and low quality paper(s) will be rejected.

(4) Poster presentation

Anyone, including students, can submit a paper as a poster presentation.

Please follow the IEEE format provided by the committee.

Paper should not exceed **2 printed pages**. The paper will not be published in Xplore. The papers are confidential within IMFEDK and are not to be brought out. All submitted papers will be reviewed by the Committee, and low quality paper(s) will be rejected.

(5) **Awards** will be presented to excellent papers by the Committee

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